


## APPLICATION DATA SHEET

Electronic Version

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<b>Title of Invention</b>	METHOD OF SOLDERING SEMICONDUCTOR PART AND MOUNTED STRUCTURE OF SEMICONDUCTOR PART		
Application Type : regular, Attorney Docket Number : 22040-00034-US1			
Correspondence address: Customer Number: 30678 			
Priority Data: Doc.No: 2003-291770; Country -JP ; Date: 2003-08-11 us-priority-claimed			
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